

PUBLICATION NUMBER : 10256415
PUBLICATION DATE : 25-09-98

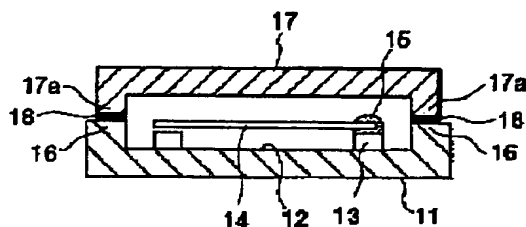
APPLICATION DATE : 10-03-97
APPLICATION NUMBER : 09072728

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INT.CL. : H01L 23/10 H01L 23/02 H01L 41/08
H01L 41/09 H03H 3/02 H03H 9/02

TITLE : STRUCTURE OF PACKAGE OF
PIEZOELECTRIC DEVICE



ABSTRACT : PROBLEM TO BE SOLVED: To reduce the cost and increase the productivity by joining and sealing a base and a cap with a sealing agent having a higher melting point than a degradation temperature of a conductive adhesive.

SOLUTION: In a package, one end of a piezoelectric element 14 such as a quartz element board is fixed with a silicon conductive adhesive 15 to a pedestal 13 in a recessed section 12 formed on an upper face of a ceramic base 11. Then, an upper face of a ring-shaped projection 16 of the base 11 which surrounds the recessed section 12 and, for example, a ceramic cap 17 are joined with a sealing means (sealing agent) made of low melting point glass 18 to airtightly seal the piezoelectric element 14. In this case, a melting point of the adhesive 15 is lower than that of the low temperature glass 18 which is a sealing means. Therefore, the sealing of the package can be done with low melting point glass without heating the adhesive in the base 11 to an extremely high temperature. By this method, a sealing structure of a high reliability can be realized while maintaining the high strength against a drop and impact test which is a merit of a silicon adhesive.

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